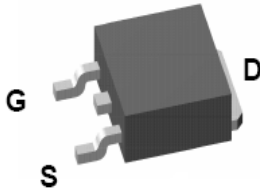


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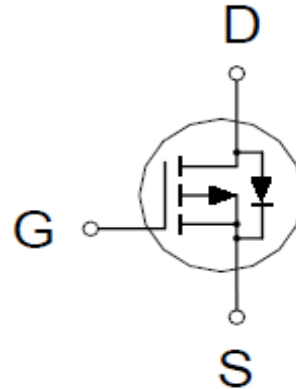
P-Channel Logic Level Enhancement Mode MOSFET

PRODUCT SUMMARY

$V_{(BR)DSS}$	$R_{DS(ON)}$	I_D
-30V	30mΩ @ $V_{GS} = -10V$	-18A



TO-252



ABSOLUTE MAXIMUM RATINGS ($T_C = 25\text{ °C}$ Unless Otherwise Noted)

PARAMETERS/TEST CONDITIONS		SYMBOL	LIMITS	UNITS
Drain-Source Voltage		V_{DS}	-30	V
Gate-Source Voltage		V_{GS}	±20	V
Continuous Drain Current	$T_C = 25\text{ °C}$	I_D	-18	A
	$T_C = 100\text{ °C}$		-12	
Pulsed Drain Current ¹		I_{DM}	-30	
Power Dissipation	$T_C = 25\text{ °C}$	P_D	50	W
	$T_C = 70\text{ °C}$		20	
Operating Junction & Storage Temperature Range		T_j, T_{stg}	-55 to 150	°C

THERMAL RESISTANCE RATINGS

THERMAL RESISTANCE	SYMBOL	TYPICAL	MAXIMUM	UNITS
Junction-to-Case	$R_{\theta JC}$		2.5	°C / W
Junction-to-Ambient	$R_{\theta JA}$		70	

¹Pulse width limited by maximum junction temperature.

²Duty cycle ≤1%

P3003EDG

P-Channel Logic Level Enhancement Mode MOSFET

ELECTRICAL CHARACTERISTICS (T_C = 25 °C, Unless Otherwise Noted)

PARAMETER	SYMBOL	TEST CONDITIONS	LIMITS			UNITS
			MIN	TYP	MAX	
STATIC						
Drain-Source Breakdown Voltage	V _{(BR)DSS}	V _{GS} = 0V, I _D = -250μA	-30			V
Gate Threshold Voltage	V _{GS(th)}	V _{DS} = V _{GS} , I _D = -250μA	-1	-1.5	-3.0	V
Gate-Body Leakage	I _{GSS}	V _{DS} = 0V, V _{GS} = ±20V			±250	μA
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} = -24V, V _{GS} = 0V			1	μA
		V _{DS} = -20V, V _{GS} = 0V, T _J = 125°C			10	
On-State Drain Current ¹	I _{D(ON)}	V _{DS} = -5V, V _{GS} = -10V	-30			A
Drain-Source On-State Resistance ¹	R _{DS(ON)}	V _{GS} = -5V, I _D = -10A		42	52	mΩ
		V _{GS} = -10V, I _D = -18A		24	30	
Forward Transconductance ¹	g _{fs}	V _{DS} = -10V, I _D = -18A		16		S
DYNAMIC						
Input Capacitance	C _{iss}	V _{GS} = 0V, V _{DS} = -10V, f = 1MHz		970		pF
Output Capacitance	C _{oss}			370		
Reverse Transfer Capacitance	C _{rss}			180		
Total Gate Charge ²	Q _g	V _{DS} = 0.5V _{(BR)DSS} , V _{GS} = -10V, I _D = -18A		28	40	nC
Gate-Source Charge ²	Q _{gs}			6		
Gate-Drain Charge ²	Q _{gd}			12		
Turn-On Delay Time ²	t _{d(on)}	V _{DS} = -15V, I _D ≅ -10A, V _{GS} = -10V, R _{GS} = 6Ω		20		nS
Rise Time ²	t _r			17		
Turn-Off Delay Time ²	t _{d(off)}			180		
Fall Time ²	t _f			75		
SOURCE-DRAIN DIODE RATINGS AND CHARACTERISTICS (T_C = 25 °C)						
Continuous Current	I _S				-18	A
Forward Voltage ¹	V _{SD}	I _F = -1A, V _{GS} = 0V			-1.2	V
Reverse Recovery Time	t _{rr}	I _F = -5A, dI _F /dt = 100A / μS		15.5		nS
Reverse Recovery Charge	Q _{rr}				7.9	

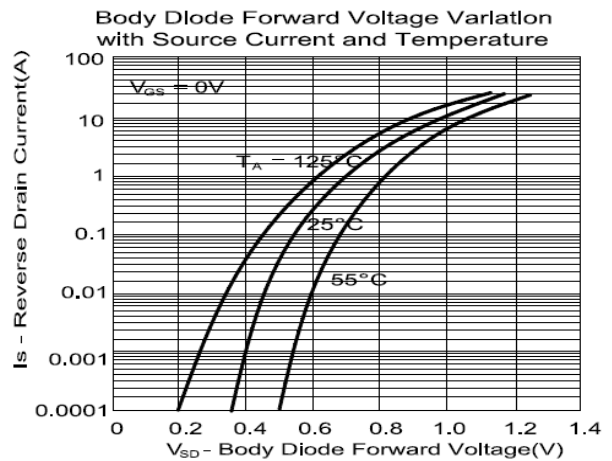
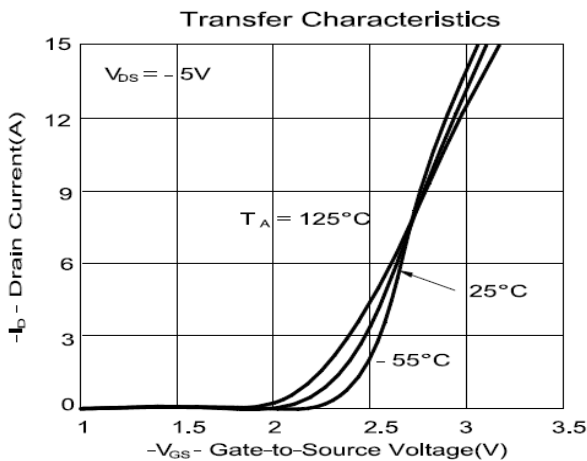
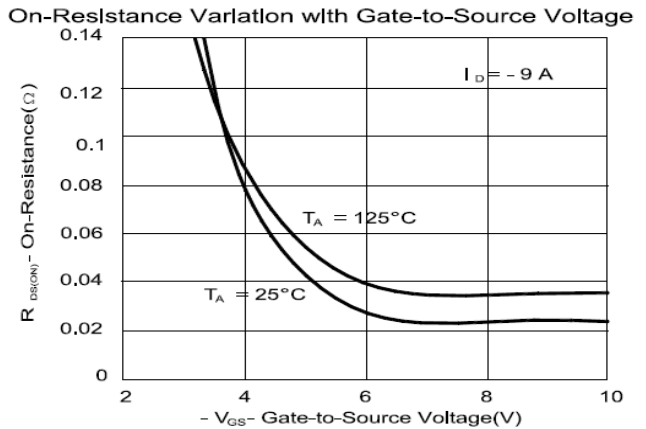
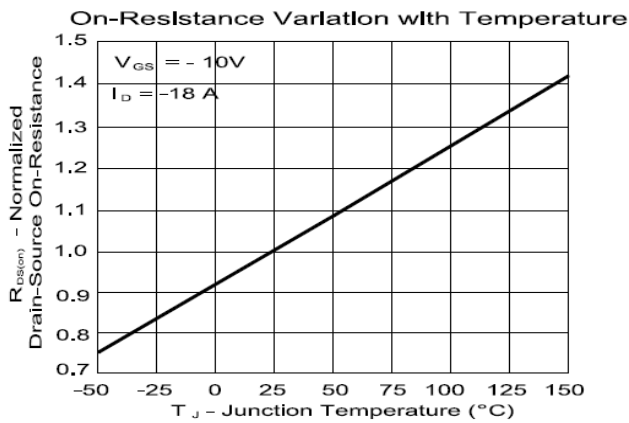
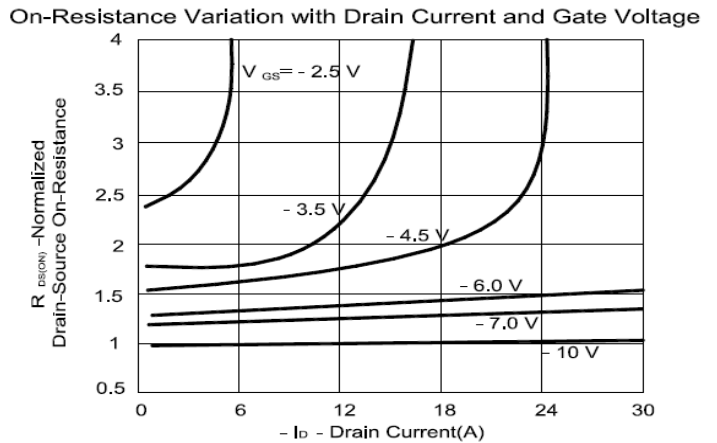
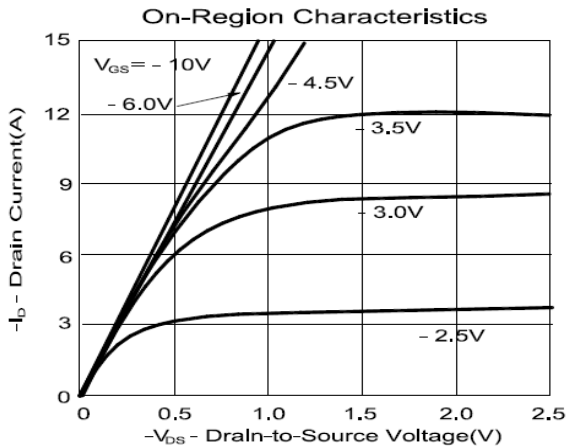
¹Pulse test : Pulse Width ≤ 300 μsec, Duty Cycle ≤ 2%.

²Independent of operating temperature.

³Pulse width limited by maximum junction temperature.

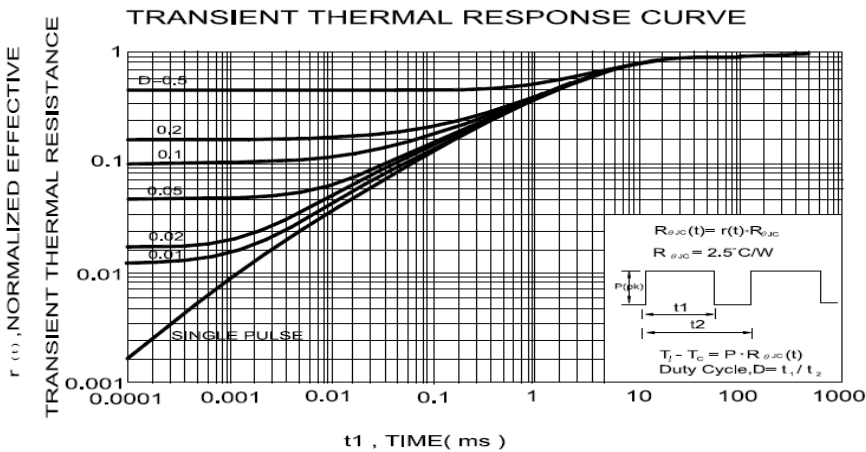
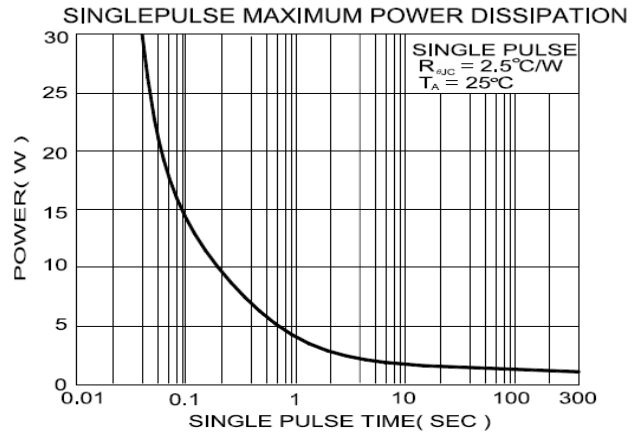
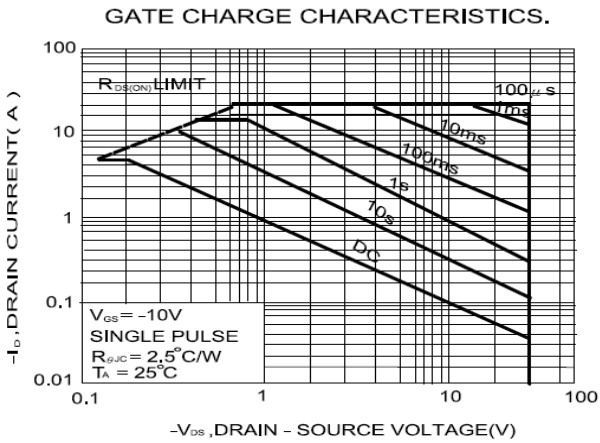
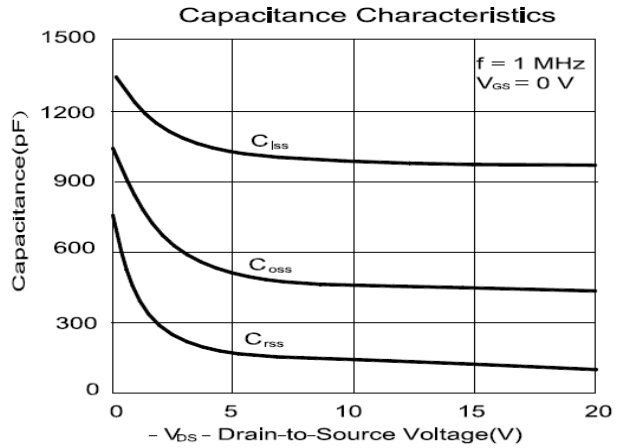
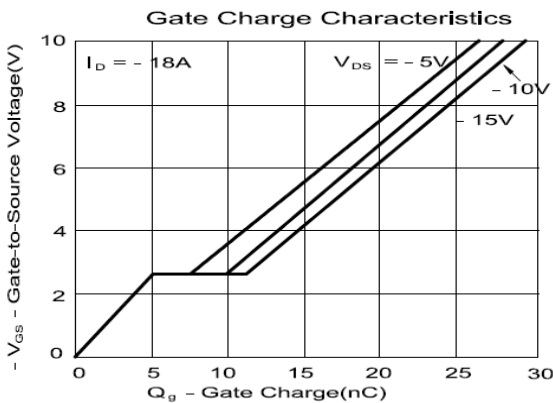
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P-Channel Logic Level Enhancement Mode MOSFET



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P-Channel Logic Level Enhancement Mode MOSFET



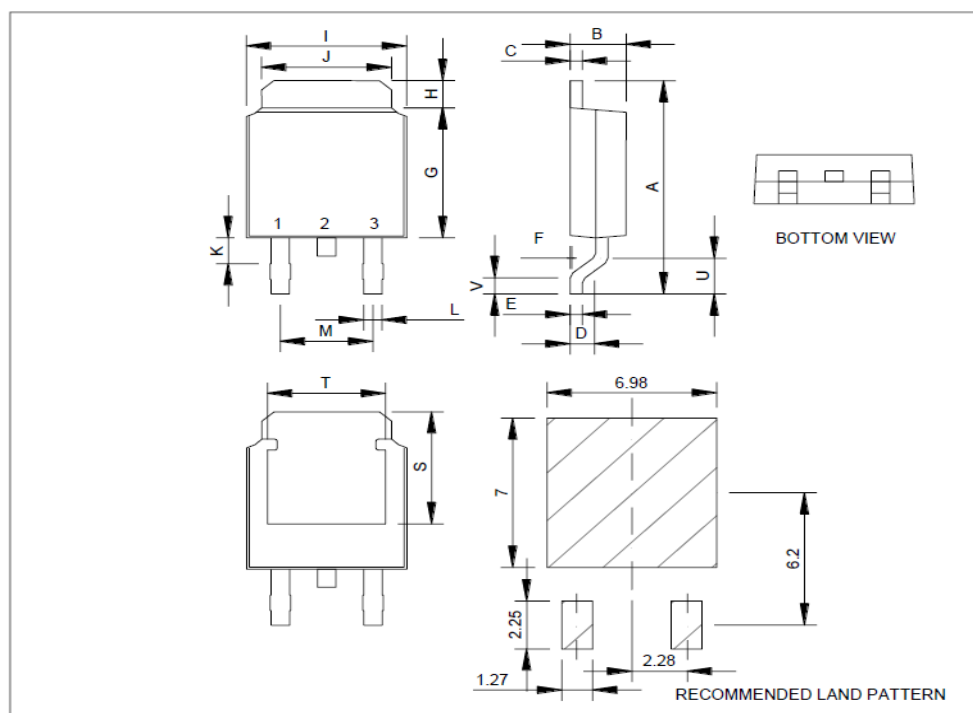
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P-Channel Logic Level Enhancement Mode MOSFET

Package Dimension

TO-252 (DPAK) MECHANICAL DATA

Dimension	mm			Dimension	mm		
	Min.	Typ.	Max.		Min.	Typ.	Max.
A	8.9	10	10.41	J	4.8		5.64
B	2.1	2.2	2.4	K	0.15		1.1
C	0.4	0.5	0.61	L	0.4	0.76	0.89
D	0.82	1.2	1.5	M	4.2	4.58	5
E	0.4	0.5	0.61	S	4.9	5.1	5.3
F	0		0.2	T	4.6	4.75	5.44
G	5.3	6.1	6.3	U	1.4		1.78
H	0.9		1.7	V	0.55	1.25	1.7
I	6.3	6.5	6.8				



*因为各家封装模具不同而外观略有所差异，不影响电性及Layout。